

L Number	Hits	Search Text	DB	Time stamp
1	0	heat with radiation same chip same bump and resist adj assist adj bonding	USPAT	2004/04/04 12:26
2	0	heat with radiation same chip same bump and resist adj assist adj bonding	USPAT; US-PPGPUB; EPO; JPO	2004/04/04 12:26
3	1	heat with radiation same chip and bump and resist adj assist adj bonding	USPAT; US-PPGPUB; EPO; JPO	2004/04/04 12:26
4	438	heat with radiation same chip and bump and bonding	USPAT; US-PPGPUB; EPO; JPO	2004/04/04 12:26
5	83	heat with radiation same chip and bump same bond	USPAT; US-PPGPUB; EPO; JPO	2004/04/04 12:27